

## **ABSTRACT**

A method and apparatus is provided for cleaning and shaping a probe tip using a multi-layer adhesive and abrasive pad. The multi-layer adhesive and abrasive pad is constructed on the surface of a support structure, such as a silicon wafer, and is made of an adhesive in contact with abrasive particles. Adhesive is applied in layers with abrasive particles in-between each layer of adhesive. Abrasive particles may vary in size and material from layer to layer to achieve cleaning, shaping and polishing objectives.

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